

MicroTCA MICROSLIM BACKPLANES



FEATURES

- Complies to MicroTCA.0 Specification Rev 1.0
- Star and Dual Star Topology options
- Optimized via signal integrity studies
- Compression-mount connectors for improved performance, reliability and field replacement capability
- Passive and active versions available
- Active version has IPMB-0 intelligence for power and cooling unit installed across the backplane
- Active version has direct PCIe, GbE, XAUI and SATA connections

BOARD SPECIFICATIONS

- 20-layer board (passive 1U), 14-layer board (active 1U), 24-layer board (3U)
- 2 oz. copper power and ground
- PCB UL listed 94V-0
- PCB FR-4 or equivalent
- PCB .195" thick (passive 1U), PCB .167" thick (active 1U), PCB .185" thick (3U version)

MECHANICAL SPECIFICATIONS

- 1U, 3U heights
- Full size modules
- Compression connectors

DESCRIPTION - PASSIVE MICROSLIM BACKPLANES

The Bustronic MicroSlim backplanes come in sizes for 1U and 3U high chassis. The 1U features slots for 6 AMC, 1 PM (Power Module), 1 MCH (MicroTCA Carrier Hub), 1 JSM (J-TAG Switch Module) and 2 CUs (Cooling Units). The 3U features 12 AMC, 4HDD (with SATA), 2 PM, 2 MCH, 1 JSM, 3 spare slots, and 2 CUs. Compression-mount connectors are used in the backplanes for increased reliability and superior (easier and more flexible) routing. If a connector is damaged in the field, it has two screws securing it in place that can be easily removed for replacing the connector. The 1U backplane features Star routing for most of the signals and point-to-point connections for the PCI Express signals. The backplanes have undergone signal integrity studies to optimize the performance.

DESCRIPTION - ACTIVE MICROSLIM BACKPLANES

The Active 1U MicroSlim Backplane is designed for low-cost MicroTCA systems with simplified power management. Instead of having IPMI management across all the FRU's, the active backplane has IPMB-0 for power and cooling unit management across the backplane. There are also direct PCIe, GbE, XAUI and SATA connections.

The active backplane features a 4-pin power connector for a pluggable PSU and a control header. There is a 12V to 3.3V converter on the backplane. But the payload and management power is managed, not distributed. Standard MCH's can be used with the active backplane.

Photo Coming Soon!



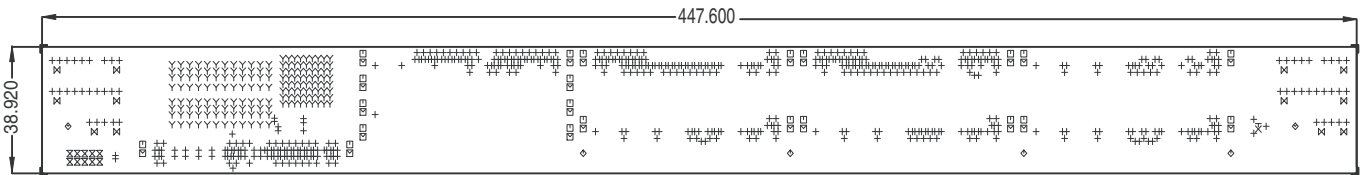
Active 1U MicroSlim

3U MicroSlim

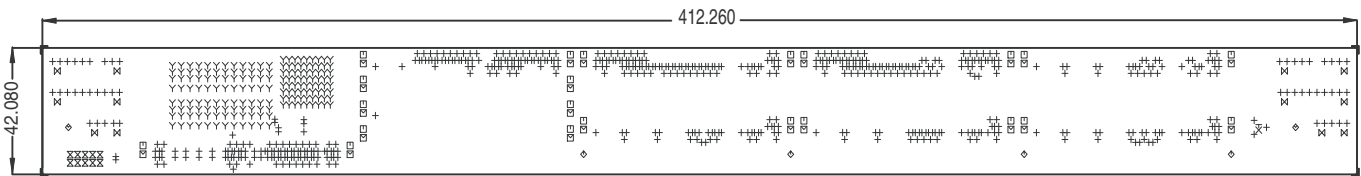
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LINE DRAWINGS

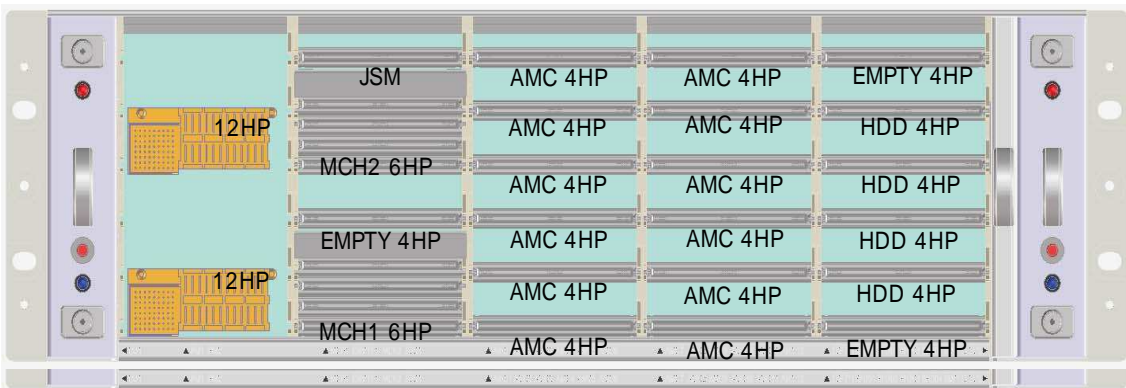
Line Drawing - Passive 1U MicroSlim



Line Drawing - Active 1U MicroSlim

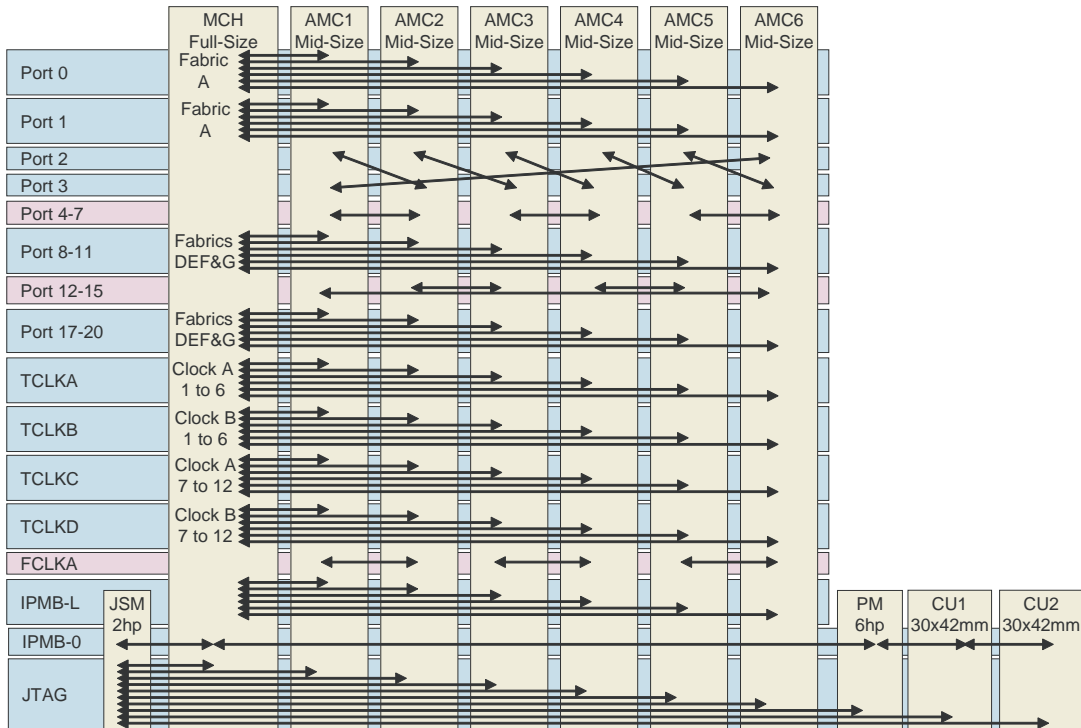


CHASSIS CONFIGURATION

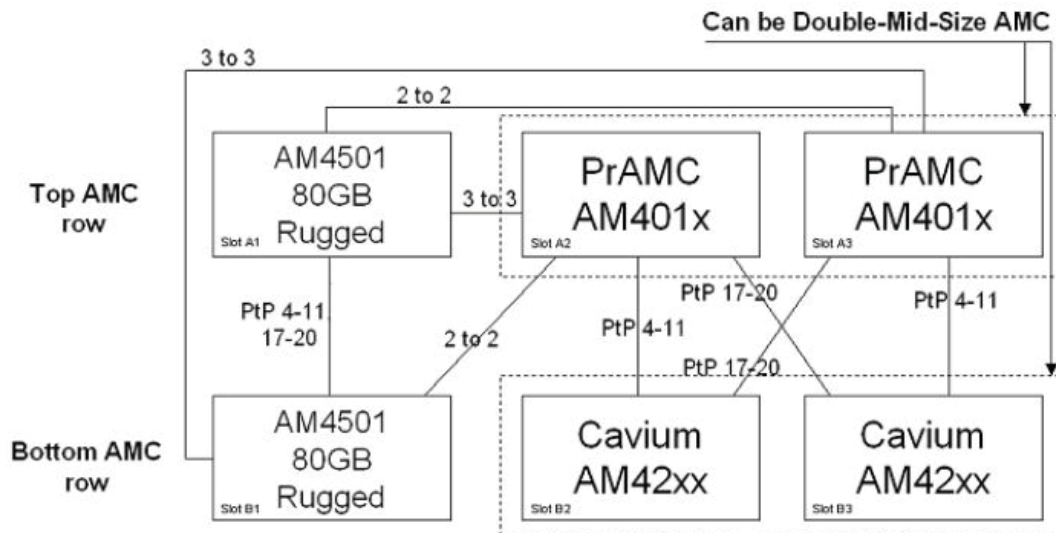


MicroTCA MICROSLIM BACKPLANES

BACKPLANE MAPPING FOR 1U MICROSLIM PASSIVE BACKPLANE



BACKPLANE MAPPING FOR 1U MICROSLIM ACTIVE BACKPLANE

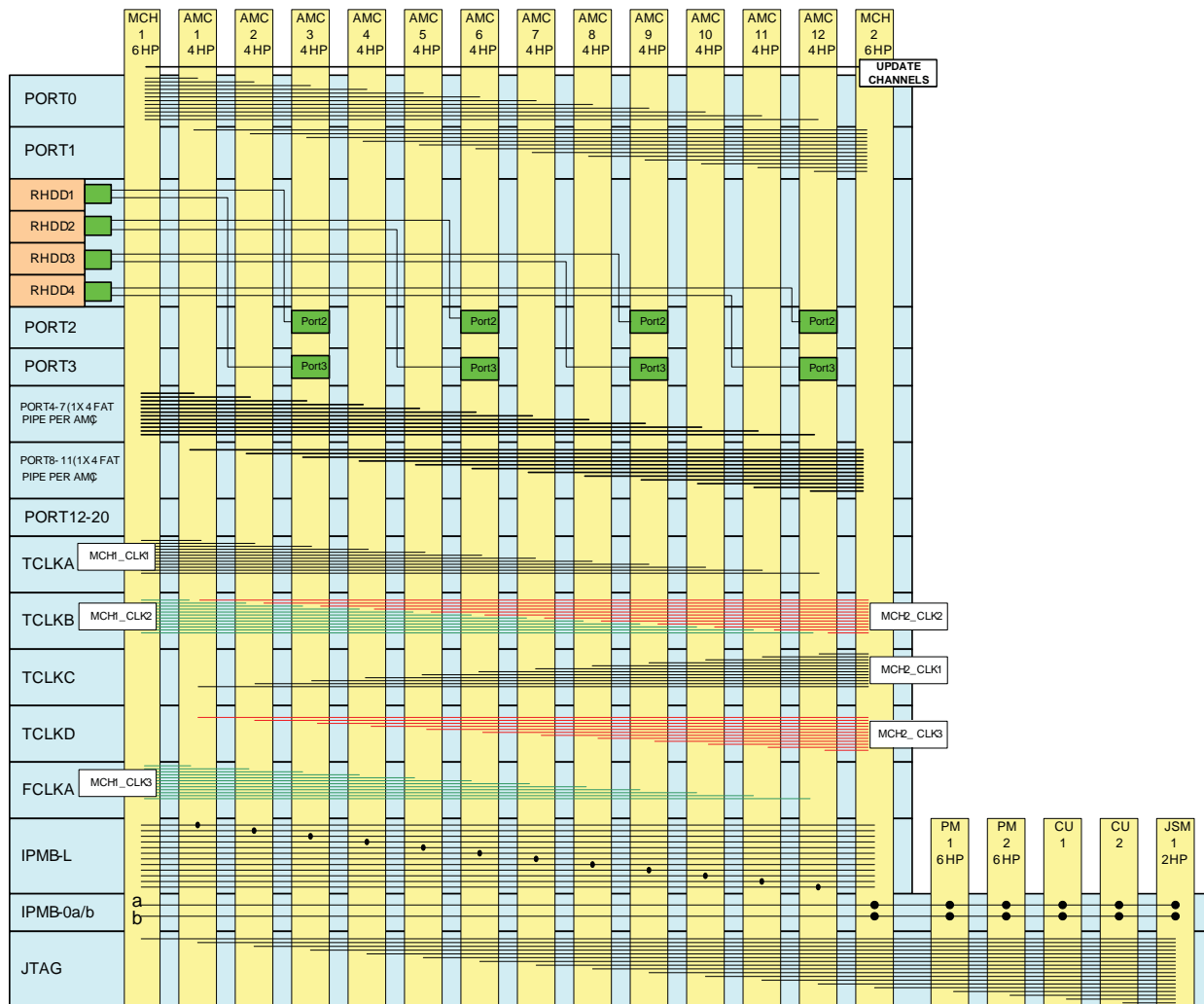


Port 0 and 1 are GbE
Port 2 and 3 are SATA

Port 4-7 are PCIe Gen 1 or 2
Port 8-11 and 17-20 are XAUI

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BACKPLANE MAPPING FOR 3U MICROSLIM BACKPLANE



ORDER INFORMATION

Height	Slots	Description	Part Number
1U	9	Passive: 6 AMC, 1 PM, 1 JSM, 1 MCH and 2 CUs (Cooling Units)	1900001880-0000R
3U	24	Passive: 12 AMC, 4 HDD (w/SATA), 2 PM, 2 MCH, 1 JSM, 3 spare slots and 2 CUs (Cooling Units)	1900001881-0000R
1U	9	Active: 6 AMC, 1 PSU connector, 1 MCH, and 2 CUs (Cooling Units)	109MTCAS07-0122